



Our Products

Contact Front Desk: **(714) 696-5332**
 Customerservice@salesandserviceinc.com
 www.salesandserviceinc.com

Perfluoropolyethers (PFPEs) Dielectric Fluid Solutions

Electronics Testing
 Vapor Phase Reflow
 Liquid Immersion Cooling
 Custom Applications



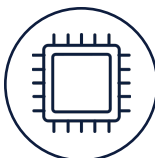
Test & Inspection Solutions

Burn-In and Test Sockets
 Burn-In and Test Printed Circuit Board
 Bond Testing (Wire, Die)
 Wafer Level 2D/3D AOI
 Surface Metrology
 Wafer Level X-Ray Inspection
 Package Level 2D/3D AOI
 Package Level 2D/3D X-Ray Inspection
 Acoustic Micro Imaging (AMI)
 Nordson WaferSense Wireless Semiconductor Measurement Devices



Materials

Bonding Wire
 Die Attach Material
 PFPE Solvents
 PVDF Thermoplastics



Metalized & Ceramic Packages

Metalized & Ceramic Lids
 Hermetic Parts
 Lead Frames (Etch, Rolled)
 Solder Preforms
 Carrier & Ceramics



Facilities Closed Loop DI Water

Waste Water Treatment
 DI Water Resin
 Chilled Water Control
 Metals Elimination & Water Recycling



Equipment Tooling

Wire Bonders (Fine/Heavy Wire, Ribbon, Tab)
 Die Bonders (Die Collets)
 Die Sorters (Pick-up Tooling)
 Fluid Dispensers (Nozzles)
 Wafer/Thin Film Probers (Four Point Probes)
 Solder Jet Balling
 Clip Bond Dispenser



Wafer Packaging & Assembly Equipment

Grinders, Dicing Saws & Laser Singulation/Grooving
 Die Sorters/Pick & Place



Wafer Process & Lamination Tools

Photopolymer Film Lamination
 DIE Attach Film Lamination
 Dry Metal Lift Off
 BG & Temporary Bonding Film Lamination



Advanced Packaging Solutions

Laser Selective Solder Reflow



Services

Wafer Processing
 • Dicing
 • Grinding
 • Stealth Dicing
 • Laser Grooving
 Wafer AOI
 Wafer Metrology
 Die Attach Package Development
 Transfer Molding Package
 Wire Bonder Parts & Repair

